Overview

HP 240R 14 inch G9 Notebook PC
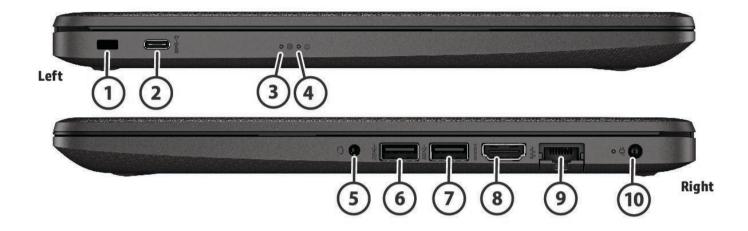

Front

1.	Internal Dual Digital Microphone	**4.**	Touchpad
2.	Webcam LED	**5.**	Touchpad Buttons
3.	Webcam	**6.**	Fingerprint Reader (Selected models)

Not all configuration components are available in all regions/countries.
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Overview

Sides

1. Mini Security Lock Slot (Lock sold in select countries)
2. SuperSpeed USB Type-C® 10 Gbps signaling rate (USB Power Delivery, DisplayPort 1.4)
3. Storage Indicator LED
4. Powe Indicator LED
5. Audio Combo Jack
6. SuperSpeed USB Type-A 5Gbps signaling rate1 port (USB 3.2 Gen 1)
7. SuperSpeed USB Type-A 5Gbps signaling rate1 port (USB 3.2 Gen 1)
8. HDMI Port (Cable Sold Separately)
9. RJ-45 / Ethernet Port
10. Power Connector

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PRODUCT NAME

HP 240R 14 inch G9 Notebook PC

OPERATING SYSTEMS

Preinstalled   Windows 11 Pro
Windows 11 Home – HP recommends Windows 11 Pro for business [1]
Windows 11 Home Single Language – HP recommends Windows 11 Pro for business [1,2]
Windows 11 Pro Education [1]
FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.
2. This computer is preinstalled with Windows 11 Home Single Language.

PROCESSORS

Processor 3,4,5,6	Cores	Number of P-cores	Number of E-cores	Threads	L3 Cache	Max Turbo Frequency 5		Base Frequency		Intel SIPP/vPro® Enterprise
						P-cores	E-cores	P-cores	E-cores	
Intel Core i5-1345U	10 cores	2	8	12	12MB	4.7 GHz	3.5 GHz	1.6 GHz	1.2 GHz	X
Intel Core i5-1335U	10 cores	2	8	12	12MB	4.6 GHz	3.4 GHz	1.3 GHz	0.9 GHz	
Intel Core i5-1334U	10 cores	2	8	12	12MB	4.6 GHz	3.4 GHz	1.3 GHz	0.9 GHz	
Intel Core i3-1315U	6 cores	2	4	8	10MB	4.5 GHz	3.3 GHz	1.2 GHz	0.9 GHz	
Intel Core 7 150U	10 cores	2	8	12	12MB	5.4 GHz	4 GHz	1.8 GHz	1.2 GHz	
Intel Core 5 120U	10 cores	2	8	12	12MB	5 GHz	3.8 GHz	1.4 GHz	0.9 GHz	
Intel Core 5 220U	10 cores	2	8	12	12MB	5 GHz	3.8 GHz	1.4 GHz	0.9 GHz	X
Intel Core 3 100U	6 cores	2	4	8	10MB	4.7 GHz	3.3 GHz	1.2 GHz	0.9 GHz	

3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

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6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

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CHIPSET

Chipset is integrated with processor.

GRAPHICS

Integrated
Intel® Iris® X[e] Graphics [7]
Intel® UHD Graphics

Supports
Support HD decode, DX12, HDMI 1.4b [8]

Hardware acceleration for CODEC H.265/HEVC (High Efficiency Video Coding) is disabled on this platform.

7. Intel® Iris® X[e] Graphics capabilities require system to be configured with Intel® Core™ i5 or i7 processors and dual channel memory. Intel® Iris® X[e] Graphics with Intel® Core™ i5 or 7 processors and single channel memory will only function as UHD graphics.
8. HD content required to view HD images.

DISPLAY

Non-Touch
35.6 cm (14") diagonal FHD UWVA eDP + PSR, narrow bezel bent, 300 nits, 45% NTSC (1920 x 1080) [9,10,11]
35.6 cm (14") diagonal HD SVA eDP anti-glare, narrow bezel bent, 250 nits, 45% NTSC (1366 x 768) [9,10,11]

HDMI
Supports resolutions up to 1920 x 1080 external resolution @60 Hz

Display Size
14" diagonal
35.56 cm (14") diagonal

Screen to Body Ratio
78.4%

Aspect Ratio
16.9

9. HD content required to view HD images.
10. Sold separately or as an optional feature.
11. Resolutions are dependent upon monitor capability, and resolution and color depth settings.

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STORAGE AND DRIVES

Primary Storage
1 TB PCIe® NVMe™ M.2 Value Solid State Drive [12]
512 GB PCIe® NVMe™ M.2 Value Solid State Drive [12]
256 GB PCIe® NVMe™ M.2 Value Solid State Drive [12]
128 GB PCIe® NVMe™ M.2 Value Solid State Drive [12]

12. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 11) is reserved for system recovery software.

MEMORY

Maximum Memory
32 GB DDR4-3200 MHz SDRAM (2 x 16 GB) [13,14]

Memory
32 GB DDR4-3200 MHz SDRAM (2 x 16 GB) [13,14]
16 GB DDR4-3200 MHz SDRAM (1 x 16 GB) [13,14]
16 GB DDR4-3200 MHz SDRAM (2 x 8 GB) [13,14]
8 GB DDR4-3200 MHz SDRAM (1 x 8 GB) [13,14]
8 GB DDR4-3200 MHz SDRAM (2 x 4 GB) [13,14]
4 GB DDR4-3200 MHz SDRAM (1 x 4 GB) [13,14]

Memory Slots
2 SODIMM (select models) [13,14]
All slots are customer non-accessible / non-upgradeable
Supports Dual Channel Memory[14]

13. All slots are non-accessible / non-upgradeable.
14. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

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NETWORKING/COMMUNICATIONS

WLAN
Realtek 8852BE-VS (2X2) Wi-Fi® 6 Bluetooth® 5.3 Wireless Card WW WLAN [15]
Realtek 8852BE-VS (1X1) Wi-Fi® 6 Bluetooth® 5.3 Wireless Card® WLAN [15]

Miracast
Compatible with Miracast-certified devices (For Windows11) [16]

Ethernet
Integrated 10/100/1000 GbE [17]

15. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs.
16. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.
17. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

AUDIO/MULTIMEDIA

Audio
2 Integrated stereo speakers
Integrated microphone

Speaker Power
2W/4ohm

Camera
720p HD camera with Temporal Noise Reduction [9]

9. HD content required to view HD images.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard
Full size, textured, island-style keyboard

Pointing Device
Touchpad with multi-touch gesture support (PTP certified)

Function Keys
F1 - Open " How to get help in Windows 11" webpage
F2 - Brightness Down
F3 - Brightness Up
F4 - Display Switching
F5 - Blank
F6 - Mute
F7 - Volume Down
F8 -Volume Up
F9 - Previous
F10 - Play/Pause

Not all configuration components are available in all regions/countries.
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F11 - Next
F12 - Airplane mode
Microsoft Copilot Key[18]

18. Requires Windows 11 and an NPU. Timing of feature delivery and availability varies by market and device. Requires Microsoft account to log in. Where Copilot in Windows is not available, the Copilot key will lead to the Bing search engine. See http://aka.ms/WindowsAIFeatures

SOFTWARE AND SECURITY

Software
HP Connection Optimizer
HP Privacy Settings
HP Smart Support [19]
HP Support Assistance [20]
MyHP
Buy Microsoft Office (Sold separately)

Manageability Features
Touchpoint Customizer for Consumer

NOTE: To enhance brightness, level go to the Intel® Graphics Command Center app, click on System and turn off the Display Power Savings function.

Security Management
McAfee Security (30 days free trial as default) [21]
Express VPN (30 days free trial)
LastPass password manager
Discrete TPM 2.0
Fingerprint Reader [22]

19. HP Smart Support requires the HP agent to be installed. For more information about how to enable or to download HP Smart Support, please visit http://www.hp.com/smart-support. HP Services Scan is provided thru Windows Update and will check entitlement on each hardware device to determine if an HP agent-enabled service has been purchased, and will download applicable software automatically. The HP agent is a telemetry and analytics platform that provides critical data around devices and applications and is not sold as a standalone service. HP follows stringent GDPR privacy regulations and is ISO27001, ISO27701, ISO27017 and SOC2 Type2 certified for Information Security. Internet access is required. For full system requirements or to disable this feature, please visit http://www.hpdaas.com/requirements.
20. HP Support Assistant is available on Windows. For more information, please visit http://www.support.hp.com/help/hp-support-assistant.
21. 30-day McAfee® LiveSafe™ trial included. Internet access required and not included. Subscription required after expiration. See http://www.McAfee.com for more details
22. HP Sure Recover is available on select HP PCs and requires Windows 10 or Windows 11 and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on select PCs.

Not all configuration components are available in all regions/countries.
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POWER

Power Supply
HP Smart 65 W EM External AC power adapter [23]
HP Smart 45 W External AC power adapter [23]
HP Smart 65 W USB Type-C® adapter [23]

Battery
HP Long Life 3 cell, 41 Wh Li-ion Polymer[24,25]

Power Cord
1M (3.28 feet) length power cord

Battery Life
Up to 8 hours 45 minutes with 41whr battery[26]

Battery Weight
0.39 lb
0.18 kg

23. Availability may vary by country.
24. Battery is internal and not replaceable by customer. Serviceable by warranty.
25. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.
26. MobileMark 25 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.

Not all configuration components are available in all regions/countries.
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WEIGHTS & DIMENSIONS

Product Weight
Starting at 3.25 lb [27]
Starting at 1.47 kg [27]

Product Dimensions (W x D x H) [28]
324 mm (W) x 225.9 mm (D) x 9.4mm (front)/ 15mm (rear)
Maximum height 19.9 (mm)

12.75 in (W) x 8.89 in (D) x 0.37 in (front)/ 0.59 in (rear)
Maximum height 0.78 (in)

Package Dimensions (W x D x H)[29]
12-15" boxes (305mm height): 1200mm x 1000mm x 1080mm

27. Weight will vary by configuration.
28. Front height measurement is near the front edge where the chassis bottom cover taper begins. Back height measurement is near the back edge where the chassis bottom cover taper ends.
29. Learn more about HP business notebooks, tablets, and desktops at hp.com or contact your local HP sales representative.

PORTS/SLOTS

2 SuperSpeed USB Type-A 5Gbps signaling rate
1 SuperSpeed USB Type-C® 10Gbps signaling rate (USB Power Delivery, DisplayPort™ 1.4)
1 HDMI v1.4b [30]
1 RJ-45
1 AC Power
1 Headphone/mic combo jack

30. HDMI cable sold separately.

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ENVIRONMENTAL DATA

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • US ENERGY STAR® • US Federal Energy Management Program (FEMP) • EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. • TCO Certified • China Energy Conservation Program (CECP) • China State Environmental Protection Administration (SEPA) • Taiwan Green Mark • Korea Eco-label • Japan PC Green label*
Sustainable Impact Specifications	• Product Carbon Footprint • 2.3% post-consumer recycled plastic • Low halogen • Outside Box and corrugated cushions are 100% sustainably sourced and recyclable • Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable. • Bulk packaging available
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".

Energy Consumption (in accordance with US ENERGY STAR® test method)	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)	4.08 W	4.25 W	4.24 W
Normal Operation (Long idle)	0.68 W	0.69 W	0.68 W
Sleep	0.68 W	0.69 W	0.68 W
Off	0.16 W	0.18 W	0.16 W

NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)	14 BTU/hr	15 BTU/hr	15 BTU/hr
Normal Operation (Long idle)	2 BTU/hr	2 BTU/hr	2 BTU/hr
Sleep	2 BTU/hr	2 BTU/hr	2 BTU/hr
Off	1 BTU/hr	1 BTU/hr	1 BTU/hr

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	**Sound Power (L$_{WAd}$, bels)**	**Sound Pressure (L$_{pAm}$, decibels)**
Typically Configured – Idle	1.0	10
Fixed Disk – Random writes	3.1	31
Optical Drive – Sequential reads	3.5	35
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the

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	Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.		
Additional Information	- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. - This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. - This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). - This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net - Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. - This product is 93.0% recycle-able when properly disposed of at end of life.		
Packaging Materials	**External:**	PAPER/Corrugated	256 g
		PAPER/Molded pulp	171 g
	Internal:	PAPER/PAPER	8 g
		PLASTIC/Polyethylene low density-LDPE	13 g
	The plastic packaging material contains at least 0.00% recycled content.		
	The corrugated paper packaging materials contains at least 60.0% recycled content.		
RoHS Compliance	HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam. We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products. We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve. To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.		
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html): - Asbestos - Certain Azo Colorants - Certain Brominated Flame Retardants – may not be used as flame retardants in plastics - Cadmium - Chlorinated Hydrocarbons - Chlorinated Paraffins - Bis(2-Ethylhexyl) phthalate (DEHP) - Benzyl butyl phthalate (BBP) - Dibutyl phthalate (DBP)		

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	• Diisobutyl phthalate (DIBP) • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging: • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP, Inc. Corporate Environmental Information	For more information about HP's commitment to the environment:
	
	Global Citizenship Report
	    http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	    http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	  ISO 14001 certificates:
	    http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842
	    and
	    http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

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footnotes	- Percentage of ocean-bound plastic contained in each component varies by product - Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard. - External power supplies, WWAN modules, power cords, cables and peripherals excluded. 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers. - Fiber cushions made from 100% recycled wood fiber and organic materials. - Disclaimer: recycled metal is expressed as a percentage of the total weight of the metal according to ISO 14021 definitions for metal parts over 25 grams.

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SERVICE AND SUPPORT

1-year warranty and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc. [31]

31. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

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SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)

Nominal Operating Voltage	19.5V
Average Operating Power	Win 11
Integrated graphics	Yes
Max Operating Power	UMA<45W

Temperature

Operating	0° to 35° C (32° to 95° F)
Non-operating	5° to 35° C (41° to 95° F)

Relative Humidity

Operating	10% to 90 % (non-condensing)
Non-operating	5% to 95 %

Shock

Operating	40 G, 2 ms duration, half-sine
Non-operating	240 G, 2 ms duration, half-sine

Random Vibration

Operating	1.043 grams
Non-operating	3.5 grams

Altitude (unpressurized)

Operating	-15 to 3,048 m (-50 to 10,000 ft)
Non-operating	-15 to 12,192 m (-50 to 40,000 ft)

Planned Industry Standard Certifications

Regulatory Model Number	TPN-1130
CSA/UL 62368-1	Yes
ENERGY STAR®	Yes
EPEAT®	EPEAT® Gold in the United States [32]
FCC/ICES/CISPR/VCCI	Yes
CE MARKING	Yes
GS Mark	No
China CCC/SRRC	Yes
Taiwan BSMI/NCC	Yes
Korea KCC/KC/KES	Yes
Ukraine NSoC/TEC	Yes
Saudi Arabian Compliance	Yes
TCO	Yes
WW RoHS	Yes
Low Blue Light	No
MIL-STD 810H Testing	Yes[33]

32. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.net for more information.
33. MIL STD 810H testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

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QuickSpecs

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DISPLAYS

1. Actual brightness will be lower with touchscreen or HP Sure View.

NOTE: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

88196 - 14.0 in FHD (1920 x 1080) Anti-Glare UWVA LED NTSC 45 NB2X 300 eDP 1.2 w/o PSR Low-Power flat LCD Panel		
Outline Dimensions (W x H)	315.31 x 185.14(max) (with FPC)
Active Area	309.37 x 174.02
Weight	290g max.
Diagonal Size	14 (inch)
Surface Treatment	Anti-Glare
Touch Enabled	No
Contrast Ratio	1200:1 (typ)
Refresh Rate	60Hz
Brightness	300 nits (typ.)
Pixel Resolution - Format	1920 x 1080 (FHD)
Backlight	WLED
Pixel Resolution	RGB
Color Gamut Coverage	NTSC 45%
Color Depth	true 8 bits
Viewing Angle	UWVA 89/89/89/89
Low Blue Light	No
Power Consumption (W, EBL@ 150nits max/ 200nits max))	1.50W Max/1.87W Max

69485 - Panel LCD 14-in HD (1366x768) Anti-Glare WLED SVA 45percent cg 250nits eDP NWBZ ultraslim		
Outline Dimensions (W x H)	315.9+/-0.3 x 197.55 +/- 0.5
Active Area	309.4 x 173.95
Weight	285g Max
Diagonal Size	14 (inch)
Surface Treatment	Anti-Glare
Touch Enabled	No
Contrast Ratio	300:1 (typ)
Refresh Rate	60Hz
Brightness	250 nits (typ.)
Pixel Resolution - Format	1366 x 768 (HD)
Backlight	LED
Pixel Resolution	RGB
Color Gamut Coverage	NTSC 45%
Color Depth	6
Viewing Angle	SVA 45/45/15/30
Low Blue Light	No
Power Consumption (W, EBL@ 150nits max/ 200nits max))	2.52W max./2.86W max.

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STORAGE AND DRIVES

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10 and 11) is reserved for system recovery software.

86721 – 1TB PCIe 2280 NVMe Value China Solid State Drive		
	Form Factor	M.2 2280
	Capacity	1TB
	NAND Type	value
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe
	Logical Blocks	2,000,409,264
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	Pyrite

87915 – 512GB PCIe 2280 NVMe Value China Solid State Drive		
	Form Factor	M.2 2280
	Capacity	512GB
	NAND Type	value
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe
	Logical Blocks	1,000,215,216
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	Pyrite

50209 – SSD 128GB 2230 PCIe NVMe Value		
	Form Factor	M.2 2230
	Capacity	128GB
	NAND Type	value
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe
	Logical Blocks	250,069,680
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	Pyrite
	Maximum Sequential Read	up to 1600MB/s ±20%
	Maximum Sequential Write	up to 900MB/s ±20%

61597 – SSD 1TB 2280 PCIe NVMe Value		
	Form Factor	M.2 2280
	Capacity	1TB
	NAND Type	value

Not all configuration components are available in all regions/countries.

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	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe
	Logical Blocks	2,000,409,264
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	Pyrite
	Maximum Sequential Read	up to 2300MB/s ±20%
	Maximum Sequential Write	up to 2000MB/s ±20%
47267 - SSD 256GB 2280 PCIe NVMe Value	**Form Factor**	M.2 2280
	Capacity	256GB
	NAND Type	value
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe
	Logical Blocks	500,118,192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	Pyrite
	Maximum Sequential Read	up to 2300MB/s ±20%
	Maximum Sequential Write	up to 1280MB/s ±20%
47268 - SSD 512GB 2280 PCIe NVMe Value	**Form Factor**	M.2 2280
	Capacity	512GB
	NAND Type	value
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Interface	PCIe NVMe
	Logical Blocks	1,000,215,216
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	Pyrite
	Maximum Sequential Read	up to 2300MB/s ±20%
	Maximum Sequential Write	up to 1400MB/s ±20%

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NETWORKING/COMMUNICATIONS

Realtek RTL8852BE 802.11ax 2x2 Wi-Fi + Bluetooth® 5.3 Wireless Card (802.11ax 2x2, supporting gigabit data rate)[1]	**Wireless LAN Standards**	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
	Interoperability	Wi-Fi certified modules

	Frequency Band	• 802.11b/g/n/ax
		  2.402 – 2.482 GHz
		• 802.11a/n/ac/ax
		  4.9 – 4.95 GHz (Japan)
		  5.15 – 5.25 GHz
		  5.25 – 5.35 GHz
		  5.47 – 5.725 GHz
		  5.825 – 5.850 GHz

	Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: max 300Mbps • 802.11ac : max 866.7Mbps • 802.11ax : max 1201Mbps
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	Security[2]	• IEEE and WiFi certified 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • WPA3 certification • IEEE 802.11i • WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power[3]	• 802.11b : +18.5dBm minimum • 802.11g : +17.5dBm minimum • 802.11a : +18.5dBm minimum • 802.11n HT20(2.4GHz) : +15.5dBm minimum • 802.11n HT40(2.4GHz) : +14.5dBm minimum

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	• 802.11n HT20(5GHz) : +15.5dBm minimum	
	• 802.11n HT40(5GHz) : +14.5dBm minimum	
	• 802.11ac VHT80(5GHz) : +11.5dBm minimum	
	• 802.11ax HE40(2.4GHz) : +10dBm minimum	
	• 802.11ax HE80(5GHz) : +10dBm minimum	
Power Consumption	• Transmit mode :2.5 W	
	• Receive mode :2 W	
	• Idle mode (PSP) 180 mW (WLAN Associated)	
	• Idle mode :50 mW (WLAN unassociated)	
	• Connected Standby/Modern Standby: 10mW	
	• Radio disabled: 8 mW	
Power Management	ACPI and PCI Express compliant power management	
	802.11 compliant power saving mode	
Receiver Sensitivity[4]	• 802.11b, 1Mbps : -93.5dBm maximum	
	• 802.11b, 11Mbps : -84dBm maximum	
	• 802.11a/g, 6Mbps : -86dBm maximum	
	• 802.11a/g, 54Mbps : -72dBm maximum	
	• 802.11n, MCS07 : -67dBm maximum	
	• 802.11n, MCS15 : -64dBm maximum	
	• 802.11ac, MCS0 : -84dBm maximum	
	• 802.11ac, MCS9 : -59dBm maximum	
	• 802.11ax, MCS11(HE40): -57dBm maximum	
	• 802.11ax, MCS11(HE80): -54dBm maximum	
Antenna type	High efficiency antenna.	
	One embedded dual band 2.4/5 GHz antenna is provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm	
Weight	Type 2230: 2.8g	
Operating Voltage	3.3v +/- 9%	
Temperature	**Operating**	14° to 158° F (−10° to 70° C)
	Non-operating	−40° to 176° F (−40° to 80° C)
Humidity	**Operating**	10% to 90% (non-condensing)
	Non-operating	5% to 95% (non-condensing)
Altitude	**Operating**	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON	

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1/5.2/5.3 Wireless Card Technology

Bluetooth Specification	4.0/4.1/4.2/5.0/5.1/5.3 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE: 1 Mbps data rate; throughput up to 0.2 Mbps Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels

Not all configuration components are available in all regions/countries.

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	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.

1. Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Realtek RTL8852BE-VS 802.11ax 1x1 Wi-Fi 6+ Bluetooth® 5.3 Wireless Card (802.11ax 1x1) [1]	**Wireless LAN Standards**	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k
	Interoperability	Wi-Fi certified

	Frequency Band	• 802.11b/g/n/ax
		  2.402 – 2.482 GHz
		• 802.11a/n/ac/ax
		  4.9 – 4.95 GHz (Japan)
		  5.15 – 5.25 GHz
		  5.25 – 5.35 GHz
		  5.47 – 5.725 GHz
		  5.825 – 5.850 GHz

	Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: max 150Mbps • 802.11ac : 433Mbps • 802.11ax : max 600Mbps
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	Security [2]	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification

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	• WPA3 certification • IEEE 802.11i • WAPI • EAP	
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)	
Roaming	IEEE 802.11 compliant roaming between access points	
Output Power[3]	• 802.11b : +17dBm minimum • 802.11g : +16dBm minimum • 802.11a : +17dBm minimum • 802.11n HT20(2.4GHz) : +14dBm minimum • 802.11n HT40(2.4GHz) : +13dBm minimum • 802.11n HT20(5GHz) : +14dBm minimum • 802.11n HT40(5GHz) : +13dBm minimum • 802.11ac VHT80(5GHz) : +10dBm minimum • 802.11ax HE40(2.4GHz) : +12dBm minimum • 802.11ax HE80(5GHz) : +10dBm minimum	
Power Consumption	• Transmit mode :2.5 W • Receive mode :2 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode :50 mW (WLAN unassociated) • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW	
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity[4]	• 802.11b, 1Mbps : –93.5dBm maximum • 802.11b, 11Mbps : –84dBm maximum • 802.11a/g, 6Mbps : –86dBm maximum • 802.11a/g, 54Mbps : –72dBm maximum • 802.11n, MCS07 : –67dBm maximum • 802.11n, MCS15 : –64dBm maximum • 802.11ac, MCS0 : –84dBm maximum • 802.11ac, MCS9 : –59dBm maximum • 802.11ax, MCS11(HE40): –57dBm maximum • 802.11ax, MCS11(HE80): –54dBm maximum	
Antenna type	High efficiency antenna. One embedded dual band 2.4/5 GHz antenna is provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm	
Weight	Type 2230 : 2.8g	
Operating Voltage	3.3v +/- 9%	
Temperature	**Operating** **Non-operating**	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	**Operating** **Non-operating**	10% to 90% (non-condensing) 5% to 95% (non-condensing)

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Altitude	**Operating**	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED OFF – Radio ON	

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1/5.2/5.3 Wireless Card Technology

Bluetooth Specification	4.0/4.1/4.2/5.0/5.1/5.2/5.3 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.

1. Wi-Fi 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

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Realtek RTL8111HSH 10/100/1000 Integrated NIC	**Data rates supported**	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)
		100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)
		1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)
		Auto-Negotiation (Automatic Speed Selection)
		Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
	Power Management	ACPI compliant – multiple power modes
		Situation-sensitive features reduce power consumption
		Advanced link down power saving for reducing link down power consumption
		TCP/IP/UDP Checksum Offload (configurable)
		Protocol Offload (ARP & NS)
	Performance Features	Large send offload and Giant send offload
		Receiving Side Scaling
		Jumbo Frame 9K
	Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)
		PXE 2.1 Remote Boot
		Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))
		Comprehensive diagnostic and configuration software suite
		Virtual Cable Doctor for Ethernet cable status
	Management Interface	Auto MDI/MDIX Crossover cable detection

Not all configuration components are available in all regions/countries.
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POWER

Ceto 65W USBC Adapter (HP PN: L65505-00x)	**Dimensions**	3.543 x 2.008 x 1.122 in (9.0x5.1x2.85cm)	
	Weight	220g(+/-10g) (Not including power cord. Power cord varies by country.)	
	Input	100-240Vac	
		Input Efficiency	81.50% min at 115 Vac/ 230 Vac @5.00V 86.70% min at 115 Vac/ 230 Vac @9.00V 88.00% min at 115 Vac/ 230 Vac @12.00V 89.00% min at 115 Vac/ 230 Vac @15.00V 89.00% min at 115 Vac/ 230 Vac @20.00V
		Input frequency range	47 ~ 63Hz
		Input AC current	Max. 1.6 A at 90 Vac
	Output	**Output power**	5V/15W 9V/27W 12V/60W 15V/65W 20V/65W
		DC output	5V/9V/12V/15V/20V
		Hold-up time	100% load 5ms at 115 Vac input
		Output current limit	< 8.0A
	Leakage Current	Shall not exceed 40uA when tested at 250Vac/50 Hz in a normal operating condition	
	Connector	**AC Connector**	C6
		DC Connector	USB type C
	DC Cable Material	PVC	
	Environmental Design	**Operating temperature**	32˚F to 95˚F (0˚ to 35˚C)
		Non-operating (storage) temperature	-4˚F to 185˚F (-20˚ to 85˚C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950-1 and IEC62368-1 : 2018, EN62368-1:2014+A11, UL 62368-1 Agency approvals - C-UL-US, TUV/GS, TUV/PSE, EN55032 Class B, FCC Class B, CISPR32 Class B, CCC and CECP, CU(EAC), EAEU, KCC(Safety+EMC) and K-MEPS, NOM-001 and 029 NYCE, NRcan, NRCS, ISC, SEC, PSB, Argentina S-mark, Australia RCM, BIS, BSMI, UAE, UKCA DoC	

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Cupid II 45W Barrel Adapter (HP PN: L25296-01x)	Dimensions	3.74 x 1.772 x 1.043 in (9.5x4.5x2.65cm)	
	Weight	170g(+/-10g) (Not including power cord. Power cord varies by country.)	
	Input	100-240Vac	
		Input Efficiency	87.74 % at 115 Vac and 88.4 % at 230Vac
		Input frequency range	47-63 Hz
		Input AC current	Max. 1.4 A at 90 Vac
	Output	Output power	45W
		DC output	19.5V
		Hold-up time	100% load 5ms at 115 Vac input/80% load 10ms at 115 Vac input
		Output current limit	<8.0A
	Leakage Current	Shall not exceed 30uA when tested at 250Vac/50 Hz in a normal operating condition	
	Connector	AC Connector	C6
		DC Connector	4.5mm Barrel Type
	DC Cable Material	PVC	
	Environmental Design	Operating temperature	32˚ F to 95˚ F (0˚ to 35˚ C)
		Non-operating (storage) temperature	-4˚ F to 185˚ F (-20˚ to 85˚ C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950-1 and IEC62368-1 : 2018, EN62368-1:2014+A11, UL62368-1 Agency approvals - C-UL-US, TUV/GS, TUV/PSE, EN55032 Class B, FCC Class B, CISPR32 Class B, CCC and CECP, CU(EAC), EAEU, KCC(Safety+EMC) and K-MEPS, NOM-001 and 029 NYCE, NRcan, NRCS, ISC, SEC, PSB, Argentina S-mark, Australia GEMS and RCM, BIS, BSMI, UAE, UKCA DoC	

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HP 65W EM Barrel Adapter (HP PN: L25299-01x)	**Dimensions**	4.016 x 2.165 x 1.181 in (10.2x5.5x3cm)	
	Weight	250g(+/-10g) (Not including power cord. Power cord varies by country.)	
	Input	100-240Vac	
		Input Efficiency	88 % at 115 Vac and 89 % at 230Vac
		Input frequency range	47-63 Hz
		Input AC current	Max. 1.7 A at 90 Vac
	Output	**Output power**	65W
		DC output	19.5V
		Hold-up time	100% load 5ms at 115 Vac input/80% load 10ms at 115 Vac input
		Output current limit	<11.0A
	Leakage Current	Shall not exceed 30uA when tested at 250Vac/50 Hz in a normal operating condition	
	Connector	**AC Connector**	C6
		DC Connector	4.5mm Barrel Type
	DC Cable Material	PVC	
	Environmental Design	**Operating temperature**	32˚ F to 95˚ F (0˚ to 35˚ C)
		Non-operating (storage) temperature	-4˚ F to 185˚ F (-20˚ to 85˚ C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950-1 and IEC62368-1 : 2018, EN62368-1:2014+A11, UL62368-1 Agency approvals - C-UL-US, TUV/GS, EN55032 Class B, FCC Class B, CISPR32 Class B, CCC and CECP, BIS, UKCA DoC	
Ceto+ 65W USBC Adapter (HP PN: L65505-02x)	**Dimensions**	3.543 x 2.008 x 1.122 in (9.0x5.1x2.85cm)	
	Weight	220g(+/-10g) (Not including power cord. Power cord varies by country.)	
	Input	100-240Vac	
		Input Efficiency	81.50% min at 115 Vac/ 230 Vac @5.00V 86.70% min at 115 Vac/ 230 Vac @9.00V 88.00% min at 115 Vac/ 230 Vac @12.00V 89.00% min at 115 Vac/ 230 Vac @15.00V 89.00% min at 115 Vac/ 230 Vac @20.00V
		Input frequency range	47-63 Hz
		Input AC current	Max. 1.6 A at 90 Vac
	Output	**Output power**	5V/15W 9V/27W 12V/60W 15V/65W 20V/65W

Not all configuration components are available in all regions/countries.
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	DC output	5V/9V/12V/15V/20V
	Hold-up time	100% load 5ms at 115 Vac input
	Output current limit	<8.0A
Leakage Current	Shall not exceed 40uA when tested at 250Vac/50 Hz in a normal operating condition	
Connector	**AC Connector**	C6
	DC Connector	USB type C
DC Cable Material	Halogen Free	
Environmental Design	**Operating temperature**	32˚ F to 95˚ F (0˚ to 35˚ C)
	Non-operating (storage) temperature	-4˚ F to 185˚ F (-20˚ to 85˚ C)
	Altitude	0 to 16,400 ft (0 to 5000m)
	Humidity	20% to 95%
	Storage Humidity	10% to 95%
EMI and Safety Certifications	CE Mark - full compliance with LVD and EMC directives Worldwide safety standards - IEC60950-1 and IEC62368-1 : 2018, EN62368-1:2014+A11, UL 62368-1 Agency approvals - C-UL-US, TUV/GS, TUV/PSE, EN55032 Class B, FCC Class B, CISPR32 Class B, CCC and CECP, CU(EAC), EAEU, KCC(Safety+EMC) and K-MEPS, NOM-001 and 029 NYCE, NRcan, NRCS, ISC, SEC, PSB, Argentina S-mark, Australia RCM, BIS, BSMI, UAE, UKCA DoC	

HP 3-cell Long Life Li-Ion (41 WHr)	**Weight**	0.175 kg (0.385 lb)
	Cells/Type	3cell Lithium-Ion Polymer cell / 515974
	Energy	**Voltage**	11.28V / 11.34V
	Amp-hour capacity	3.635Ah / 3.62Ah
	Watt-hour capacity[1]	41Wh
Temperature	**Operating (Charging)**	32˚ to 113˚ F (0˚ to 45˚ C)
	Operating (Discharging)	14˚ to 122˚ F (-10˚ to 60˚ C)
	Optional Travel Battery Available	No

Not all configuration components are available in all regions/countries.

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AUDIO

HD Stereo Codec	Realtek ALC3247
Audio I/O Ports	One Headset Combo-Jack connector support CTIA spec
Internal Speaker Amplifier	2W class D stereo amplifier for the internal speaker only. External speakers must be powered.
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the Combo jack or integrated speaker.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 48 kHz for DAC and ADC.
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	0
Internal Speaker	Yes

FINGERPRINT READER

Sensor vendor	Elan eFSA80ST touch sensor
Sensor type	Capacitive
DPI resolution	508 DPI
Scan area	80 x 80 pixels
	FRR (False Reject Rate) / FAR (False Acceptance Rate):
False Rejection Rate	FRR ~ 2% @ 1:50K FAR
Mobile Voltage Operation	2.65V to 3.6V
Operating Temperature	32° – 95°F (0°C~ 35°C)
Current Consumption Image	50mA peak
Low Latency Wait For Finger	900 uA
Capture Rate	Capture Rate: 20 cm/sec
ESD Resistance	IEC 61000-4-2 4B (+15KV)
Detection Matrix	508 dpi / 4 x 4 mm sensor area

Not all configuration components are available in all regions/countries.
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Options and Accessories (Sold separately and availability may vary by country)

Type	Description	Part Number
Cases	HP Prelude Backpack 15.6	1E7D6AA
	HP Prelude Top Load 15.6	1E7D7AA
	HP Prelude Pro Recycle Backpack	1X644AA
	HP Prelude Pro Recycle Top Load	1X645AA
	HP Executive 15.6 Backpack	6KD07AA
	HP Renew Business 14.1" Bag	3E5F9AA
	HP Renew Business 17.3" Backpack	3E2U5AA
	HP Renew Business 14.1" Sleeve	3E2U7AA
	HP Renew Business 15.6" Bag	3E5F8AA
	HP Renew Business 17.3" Bag	3E2U6AA
	HP Renew Business 14.1" Sleeve	3E2U7AA
Hub	HP USB-C to USB-A Hub	Z6A00AA
Adapter	HP USB-C to USB 3.0 Adapter	N2Z63AA
	HP USB-C to RJ45 Adapter G2	4Z527AA
	HP USB 3.0 to Gig RJ45 Adapter G2	4Z7Z7AA
Keyboard/Combo	HP 975 USB+ Bluetooth® Dual-Mode Wireless Keyboard	3Z726AA
	HP 655 Wireless Keyboard and Mouse Combo	4R009AA
	HP 225 Wired Mouse and Keyboard Combo	286J4AA
	HP 235 Wireless Mouse and Keyboard Combo	1Y4D0AA
Mouse	HP USB Premium Wireless Mouse	1JR31AA
	HP 435 Multi-Device Wireless Mouse	3B4Q5AA
	HP Creator USB-A+Bluetooth 935 Wireless Mouse Black	1D0K8AA
Power	HP 65W Smart AC Adapter	H6Y89AA
Commodity	HP USB DVD-Writer EXT ODD	F2B56AA

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Change Log

Date of change:	Version History:		Description of change:
April 19, 2024	V1 to V2	Updated	Display Section
April 24, 2024	V2 to V3	Updated	Display Section
May7, 2024	V3 to V4	Added	Environmental Data
June 10, 2024	V4 to V5	Added	System unit Section
June 11, 2024	V5 to V6	Added	Display Section
June 17, 2024	V6 to V7	Added	Graphics Section
January 2, 2025	V7 to V8	Updated	Storage and Drives Section
January 22, 2025	V8 to V9	Updated	Battery Life Section Disclaimer
February 19, 2025	V9 to V10	Added	Processor Section
February 24, 2025	V10 to V11	Added	Storage and Drives Section
March 20, 2025	V11 to V12	Added	Processor Section

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